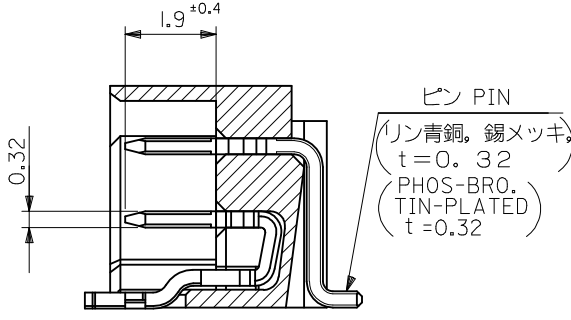
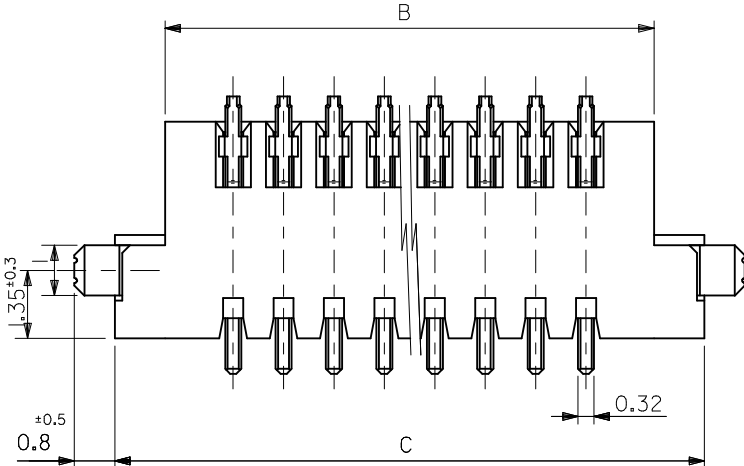


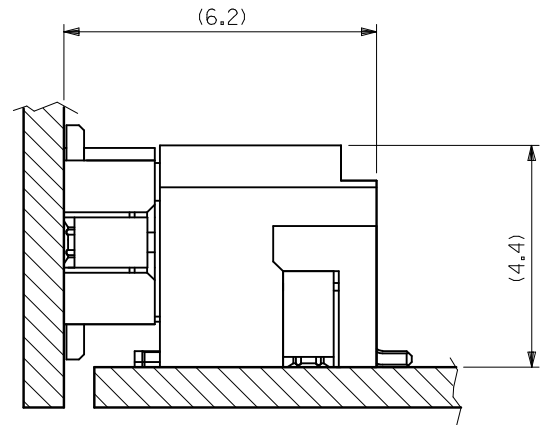
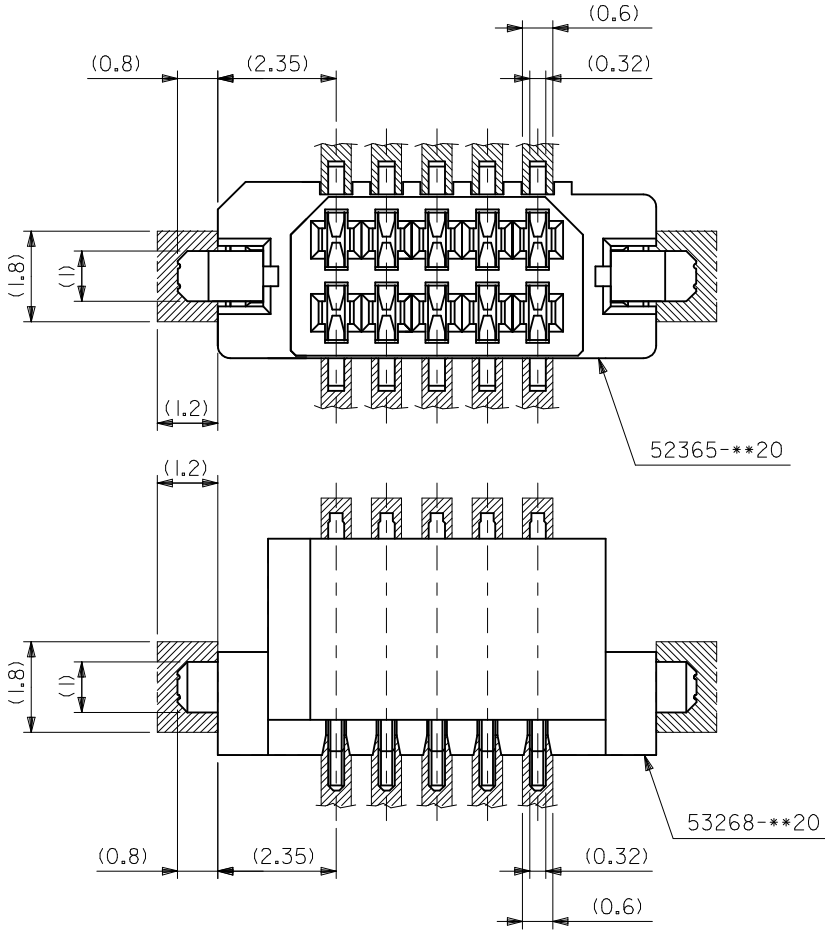
パターン参考寸法 (マウント面)  
RECOMMENDED DIM. FOR P.C. BOARD MOUNTING PATTERN (REF.)



18.7	16.7	14	53268-3020	30
15.7	13.7	11	53268-2420	24
12.7	10.7	8	53268-1820	18
6.7	4.7	2	53268-0620	6
C	B	A	MATERIAL NO.	極数 (CIRCUIT)

注記 NOTES.  
 1. 嵌合相手 : 52365-\*\*\*10 , 52365-\*\*\*20  
 MATES WITH : 52365-\*\*\*10 , 52365-\*\*\*20  
 2. ハウジングの底面 G からの金具及びターミナル半田付面のズレ量は  
 上方向 0.1 MAX. 下方向 0.15 MAX. とする。  
 MISALIGNMENT OF SOLDER TAIL TIP AND FITTING NAIL FROM G  
 : UPPER DIRECTION 0.1mm MAX.  
 : LOWER DIRECTION 0.15mm MAX.  
 3. パターンハブリ止め用金具  
 FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.

REVISED EC NO: J2009-0666 DRWN: MAKURAA 2008/09/25 CHKD: T. HARYAMA 2008/09/25 APPR: NUKITA 2008/09/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	MODEL NO. 53268-***20
	10 UNDER	±0.2	DRAWN BY S. AIHARA	DATE '92/8/3	TITLE 1.0 B/B CONN. WAFER ASS'Y R/A SMT (2/2)	MATERIAL NO. 極数 (CIRCUIT)
	10 OVER 30 UNDER	±0.25	CHECKED BY M. FUKUSHIMA	DATE '92/8/4	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY M. ENOMOTO	DATE '92/8/4		DOCUMENT NO. SD-53268-011
REV	DESCRIPTION	ANGULAR ±3 °	SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	



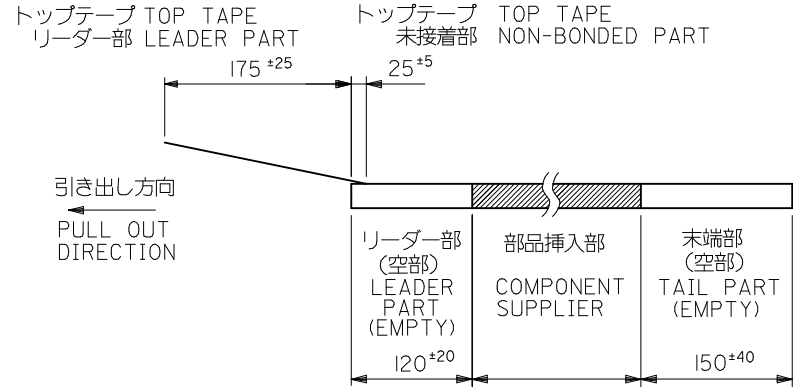
基板取付推奨レイアウト  
RECOMMENDED P.C.BOARD LAYOUT

MODEL NO. 53268-\*\*-20

REVISED EC NO: J2009-0666 DRWN: KAKURAA 2008/09/25 CHKD: T. HARIYAMA 2008/09/25 APPR: NUKITA 2008/09/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY S. AIHARA	DATE '92/8/3	TITLE 1.0 B/B CONN.WAFER ASS'Y R/A SMT (2/2)			
	10 OVER 30 UNDER	± ---	CHECKED BY M. FUKUSHIMA	DATE '92/8/4				
	30 OVER	± ---	APPROVED BY M. ENOMOTO	DATE '92/8/4	MOLEX INCORPORATED			
	ANGULAR ± --- °		MATERIAL NO.					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-53268-011		2 OF 2		

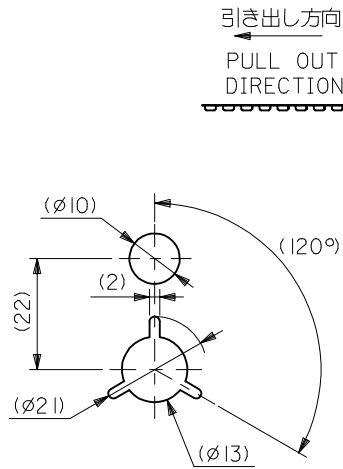
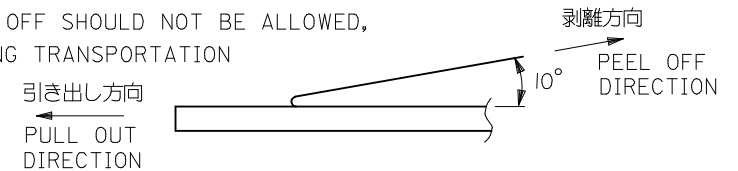
注記 NOTES

1. 梱包数量: 1000個/リール NUMBER OF CONNECTORS: 1000PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH

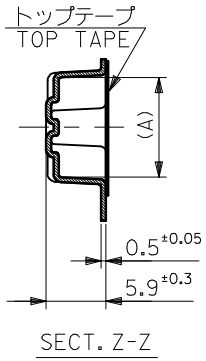
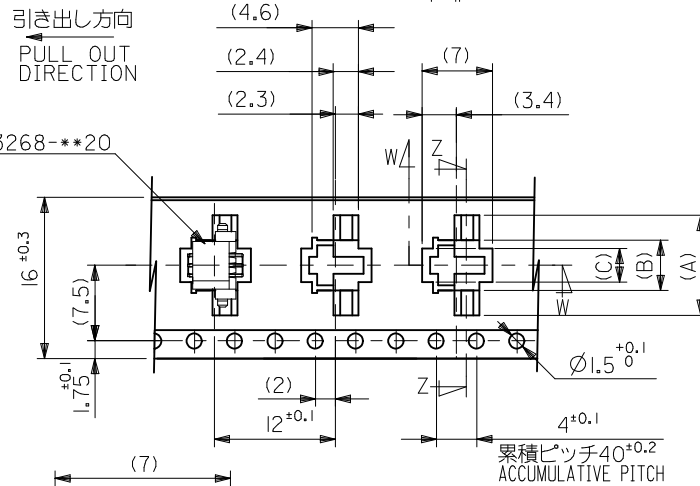
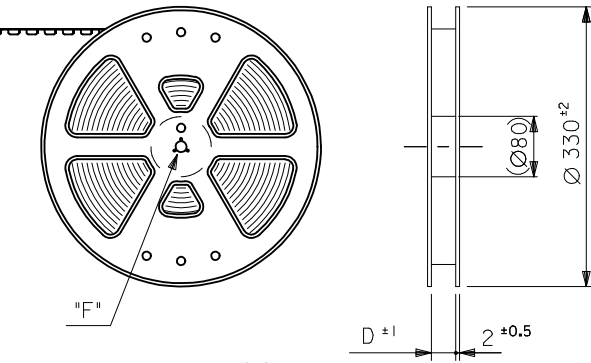


3. トップテープの剥離強度: (剥離方向は下図参照)  
60gf MAX. 尚、本規格値は、出荷時に適用。  
(但し、輸送時に剥離が発生しない事。)

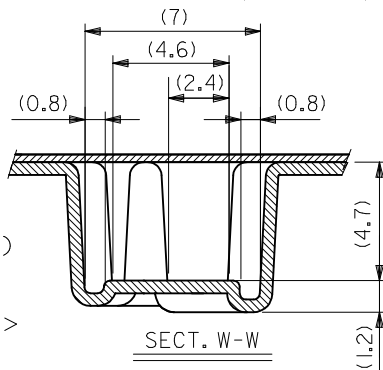
PEELING OFF FORCE OF TOP TAPE  
60gf MAX. (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
PEEL OFF SHOULD NOT BE ALLOWED,  
DURING TRANSPORTATION



DETAIL "F"



SECT. Z-Z



SECT. W-W

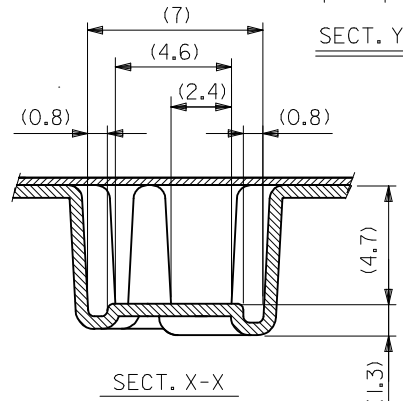
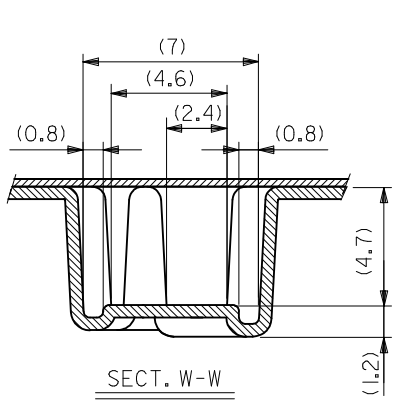
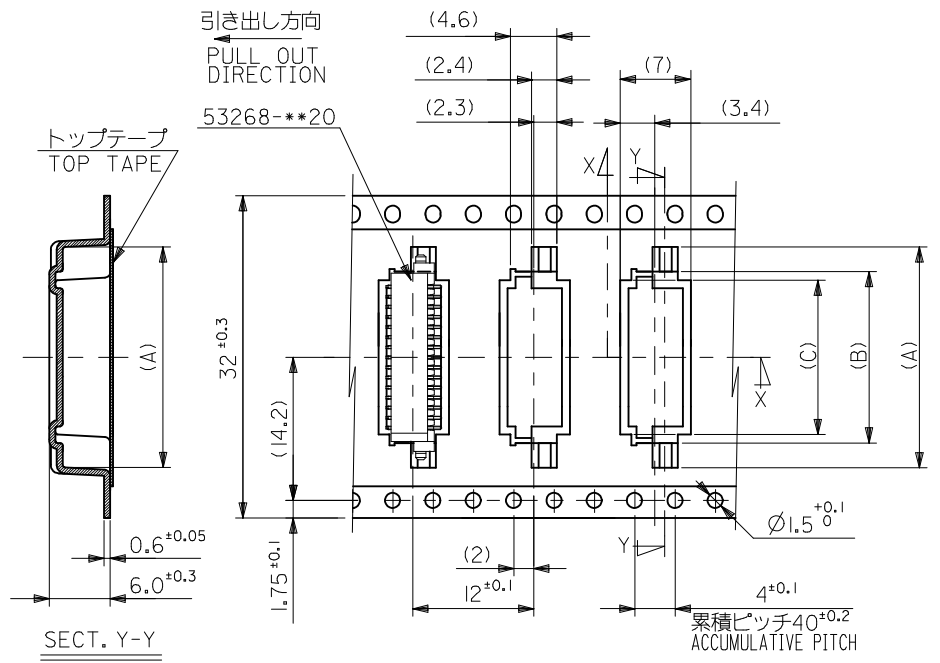
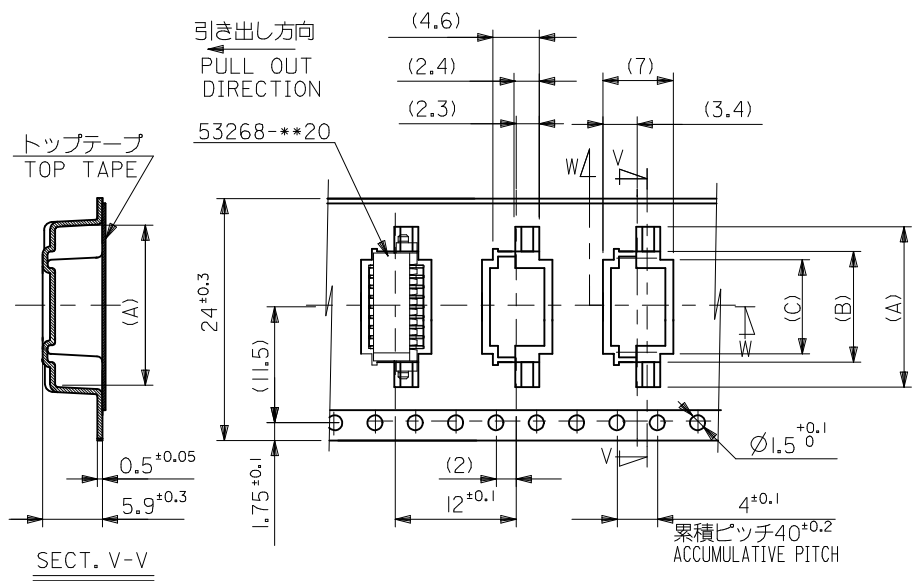
4. 材料

キャリアテープ: ポリプロピレン (PP)  
トップテープ: PET, PE, PEF  
リール: ポリスチレン (PS)  
<リサイクル材を含む>

MATERIAL  
CARRIER TAPE: POLYPROPYLENE  
TOP TAPE: PET, PE, PEF  
REEL: POLYSTYRENE (PS)  
<RECYCLE MATERIAL CONTAINED>

16	17.5	3.1	5	9.9	53268-0691	6
キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT
					MODEL NO.	53268-***91

REVISED EC NO: J2009-0666 DRWN: MAKURAA 2008/09/25 CHKD: T. HARUYAMA 2008/09/25 APPR: NUKITA 2008/09/25	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY T. HARUYAMA	DATE '90/5/8	TITLE 1.0 BTB CONN WAFER ASSY RA SMT EMBSTP PKG (1/2)		
		10 OVER 30 UNDER	± ---	CHECKED BY T. ITO	DATE '00/12/6	APPROVED BY M. FUKUSHIMA		
		30 OVER	± ---	APPROVED BY M. FUKUSHIMA	DATE '00/12/6	MATERIAL NO. SEE TABLE		
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DOCUMENT NO. SD-53268-012		SHEET NO. 1 OF 2		
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



32	33.5	15.15	17	21.9	53268-3091	30
		12.15	14	18.9	53268-2491	24
24	25.5	9.1	11	15.9	53268-1891	18
キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2009-0666 DRWN: MAKURAA 2008/09/25 CHKD: T. HARUYAMA 2008/09/25 APPR: NUKITA 2008/09/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 53268-**-91
	10 UNDER	± ---	DRAWN BY T. HARUYAMA	DATE '90/5/8	TITLE 1.0 BTB CONN WAFER ASSY RA SMT EMBSTP PKG (2/2)		
	10 OVER 30 UNDER	± ---	CHECKED BY T. ITO	DATE '00/12/6	APPROVED BY M. FUKUSHIMA '00/12/6		
	30 OVER	± ---	MATERIAL NO.		MOLEX INCORPORATED		
	ANGULAR ± --- °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		DOCUMENT NO. SD-53268-012	SHEET NO. 2 OF 2
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					